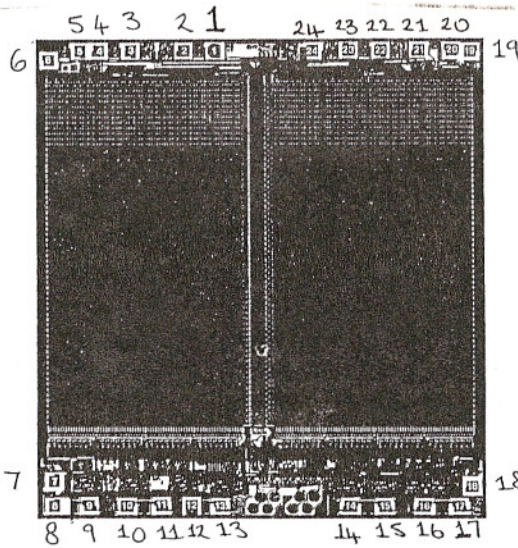




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad	Function	Pad	Function	Pad	Function
1	A7	9	DQ0	17	DQ7
2	A6	10	DQ1	18	E
3	A5	11	DQ2	19	A10
4	A4	12	GND	20	G
5	A3	13	DQ3	21	W
6	A2	14	DQ4	22	A9
7	A1	15	DQ5	23	A8
8	A0	16	DQ6	24	V _{cc}

E & O E. Dice can be supplied to this layout only if it forms part of a specification or the chip identification, if below, is requested. Chip back potential is the level at which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated above. If no potential is given the chip back should be isolated. Nominal metallisation thicknesses are based on manufacturer's information. 1 mil. = 0.001 inch. Tolerance ±3 mils.

Topside Metal: Al
Backside: Si
Backside Potential:
Mask Ref:
Bond Pads : .004 min

APPROVED BY: CB
MFG: Harris

DIE SIZE: .200" x .187"
THICKNESS: .020"

DATE: 2/6/01
P/N: HM6516B

DG 10.1.2
 Rev A 3-4-99